

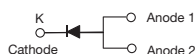


## High Current Density Standard Avalanche Surface Mount Rectifiers

### eSMP® Series



TO-277A (SMPC)



### FEATURES

- Very low profile - typical height of 1.1 mm
- Ideal for automated placement
- Glass passivated chip junction
- Controlled avalanche characteristics
- Low leakage current
- High forward surge capability
- AEC-Q101 qualified
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- **Halogen-free according to IEC 61249-2-21 definition**

AUTOMOTIVE  
GRADE  
Available



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	4.0 A
$V_{RRM}$	200 V to 1000 V
$I_{FSM}$	100 A
$E_{AS}$	20 mJ
$V_F$ at $I_F = 4$ A	0.92 V
$T_J$ max.	175 °C

### TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters and freewheeling diodes for consumer, automotive and telecommunication.

### MECHANICAL DATA

**Case:** TO-277A (SMPC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS compliant, and automotive grade

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix meets JESD 201 class 2 whisker test

### MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	AS4PD	AS4PG	AS4PJ	AS4PK	AS4PM	UNIT
Device marking code		AS4D	AS4G	AS4J	AS4K	AS4M	
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
Maximum DC forward current (fig. 1)	$I_F^{(1)}$	4.0					A
	$I_F^{(2)}$	2.4					
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	100					A
Non-repetitive avalanche energy at $T_J = 25$ °C	$I_{AS} = 2.5$ A max.	20					mJ
	$I_{AS} = 1.0$ A typical	30					
Operating junction and storage temperature range	$T_J, T_{STG}$	- 55 to + 175					°C

### Notes

(1) Mounted on 20 mm x 20 mm pad areas, 1 oz. FR4 PCB

(2) Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 2.0\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.962	-	V
	$I_F = 4.0\text{ A}$			1.044	1.10	
	$I_F = 2.0\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.822	-	
	$I_F = 4.0\text{ A}$			0.922	0.98	
Reverse current	rated $V_R$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.35	10	$\mu\text{A}$
		$T_A = 125\text{ }^\circ\text{C}$		75	150	
Typical reverse recovery time	$I_F = 0.5\text{ A}$ , $I_R = 1.0\text{ A}$ , $I_{rr} = 0.25\text{ A}$		$t_{rr}$	1.8	-	$\mu\text{s}$
Typical junction capacitance per diode	4.0 V, 1 MHz		$C_J$	60	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 40\text{ ms}$ 

THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	AS4PD	AS4PG	AS4PJ	AS4PK	AS4PM	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)}$	80					$^\circ\text{C/W}$
	$R_{\theta JM}^{(2)}$	5					

**Notes**(1) Free air, mounted on recommended PCB 1 oz. pad area; thermal resistance  $R_{\theta JA}$  - junction to ambient(2) Units mounted on PCB with 20 mm x 20 mm copper pad areas, 1 oz. FR4 PCB;  $R_{\theta JM}$  - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
AS4PJ-M3/86A	0.10	86A	1500	7" diameter plastic tape and reel
AS4PJ-M3/87A	0.10	87A	6500	13" diameter plastic tape and reel
AS4PJHM3/86A <sup>(1)</sup>	0.10	86A	1500	7" diameter plastic tape and reel
AS4PJHM3/87A <sup>(1)</sup>	0.10	87A	6500	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified



**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

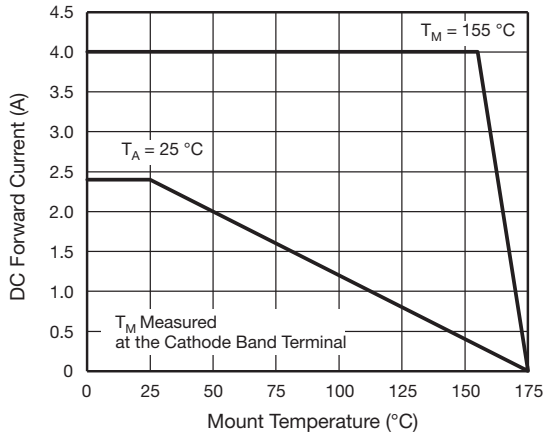


Fig. 1 - Maximum Forward Current Derating Curve

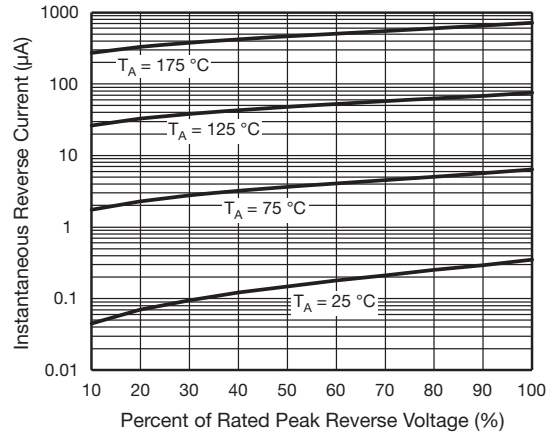


Fig. 4 - Typical Reverse Leakage Characteristics

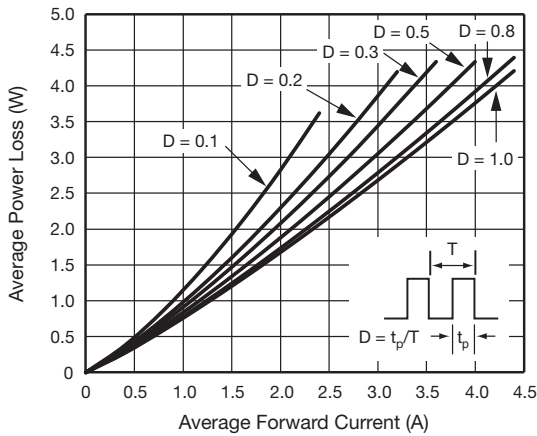


Fig. 2 - Forward Power Loss Characteristics

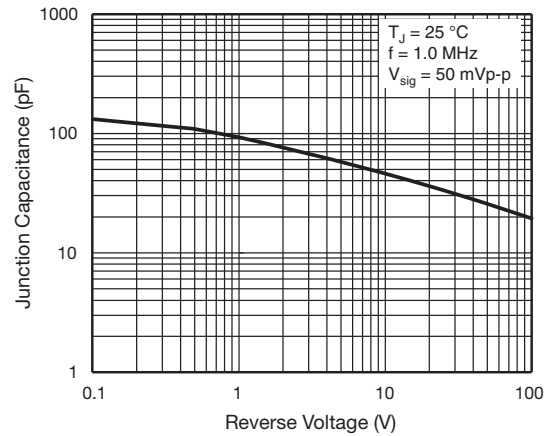


Fig. 5 - Typical Junction Capacitance

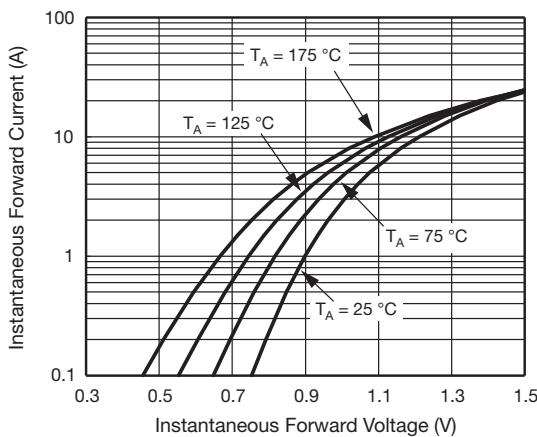


Fig. 3 - Typical Instantaneous Forward Characteristics

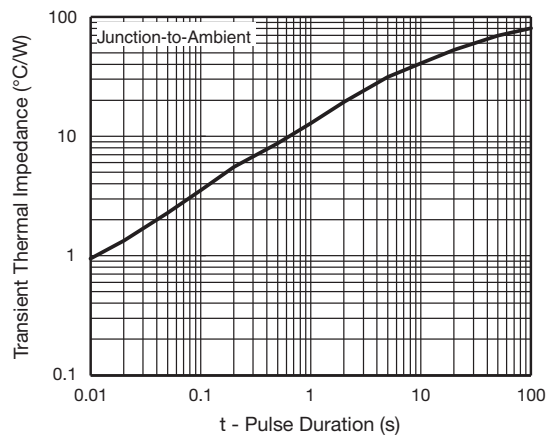
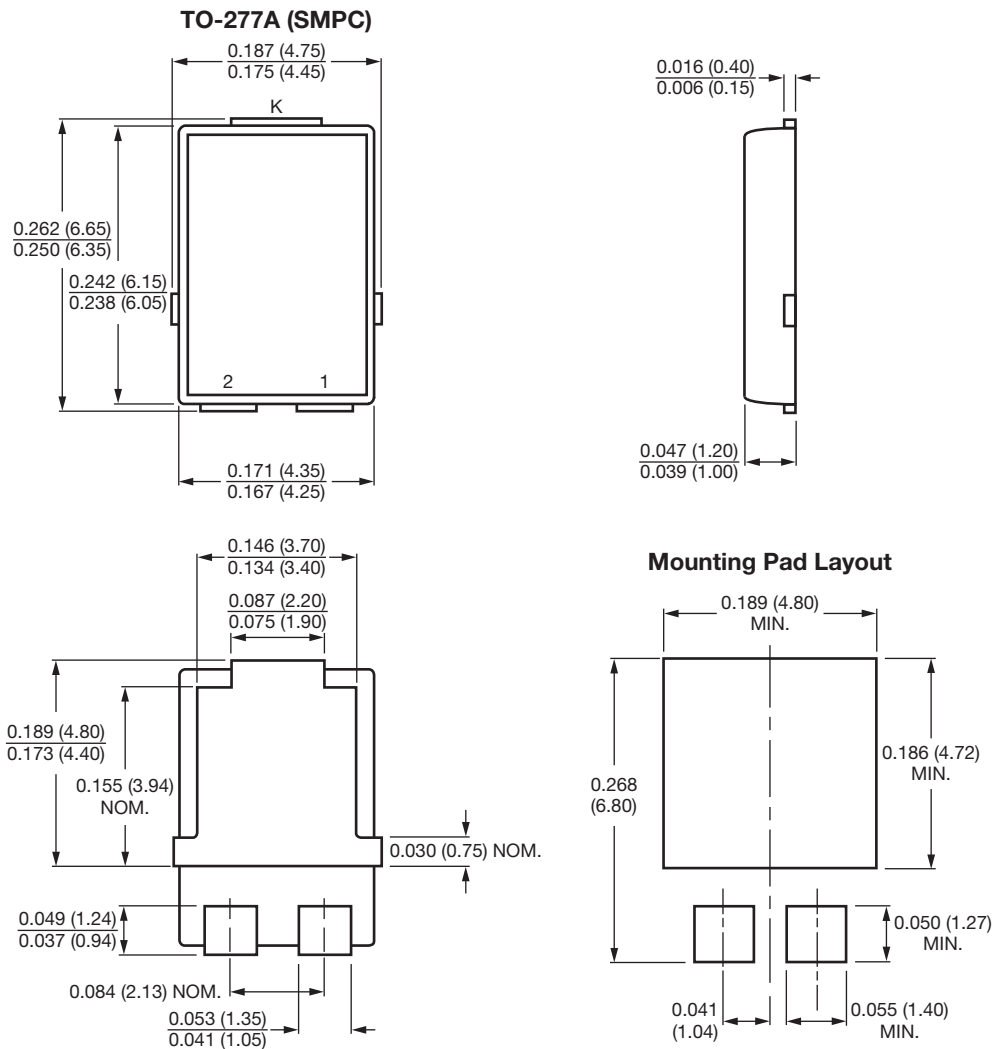


Fig. 6 - Typical Transient Thermal Impedance



**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)



Conform to JEDEC TO-277A



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